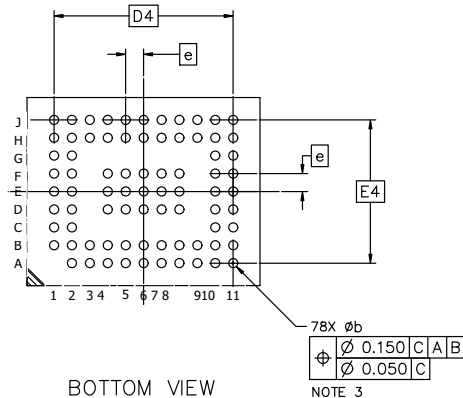
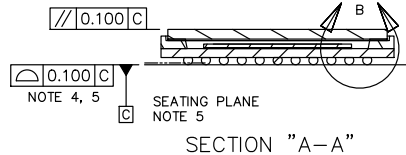
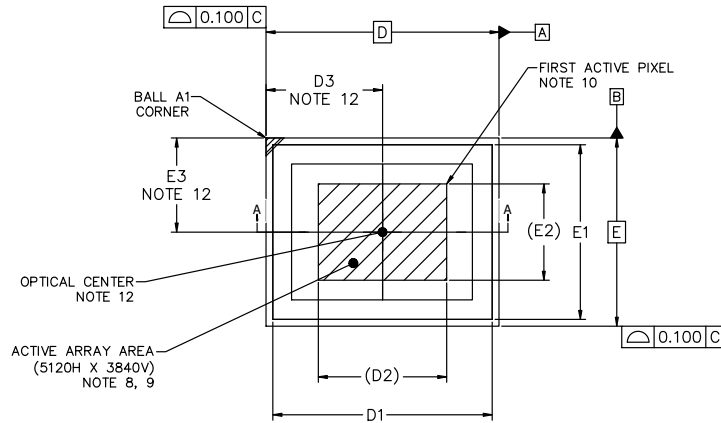
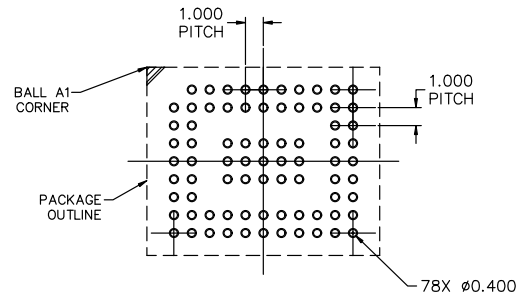
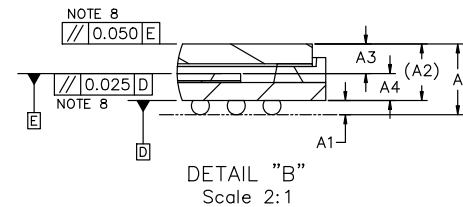


PBGA78 13.00x10.50x1.57, 1.00P
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MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	2.100
A1	0.350	0.400	0.450
A2	1.575 REF		
A3	0.725	0.825	0.925
A4	0.650	0.750	0.850
b	0.450	0.500	0.550
D	13.000 BSC		
D1	12.200	12.250	12.300
D2	7.168 REF		
D3	6.400	6.500	6.600
D4	10.000 BSC		
E	10.500 BSC		
E1	9.700	9.750	9.800
E2	5.376 REF		
E3	5.150	5.250	5.350
E4	8.000 BSC		
e	1.000 BSC		



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- CONTROLLING DIMENSION: MILLIMETERS [mm].
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- GLASS: 0.550 THICKNESS; REFRACTIVE INDEX = 1.52.
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.275 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 1^\circ$.
- REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- PACKAGE CENTER (X, Y) = (0.000, 0.000).
- OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).
- PLAIN COVER GLASS WITHOUT AR COATING.

RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

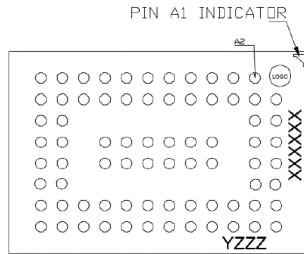
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**GENERIC
MARKING DIAGRAM***



XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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